

Complementary Low-Threshold MOSFET Pair

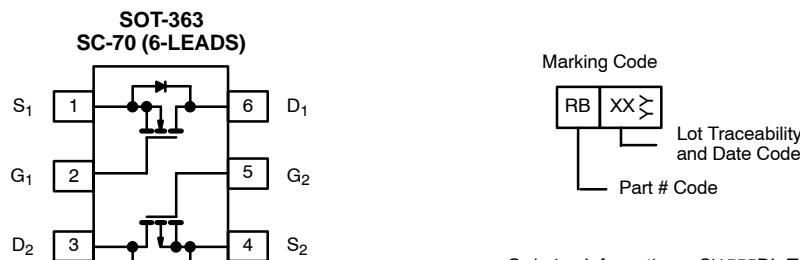
PRODUCT SUMMARY			
	V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
N-Channel	20	0.385 @ $V_{GS} = 4.5$ V	0.70
		0.630 @ $V_{GS} = 2.5$ V	0.54
P-Channel	-8	0.600 @ $V_{GS} = -4.5$ V	-0.60
		0.850 @ $V_{GS} = -2.5$ V	-0.50
		1.200 @ $V_{GS} = -1.8$ V	-0.42

FEATURES

- TrenchFET® Power MOSFET



Pb-free
Available



Ordering Information: Si1555DL-T1
Si1555DL-T1-E3 (Lead (Pb)-Free)

Top View

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C UNLESS OTHERWISE NOTED)							
Parameter		Symbol	N-Channel		P-Channel		Unit
			5 secs	Steady State	5 secs	Steady State	
Drain-Source Voltage	V_{DS}		20		-8		V
Gate-Source Voltage	V_{GS}		± 12		± 8		
Continuous Drain Current (T _J = 150°C) ^a	T _A = 25°C	I_D	± 0.70	± 0.66	-0.60	-0.57	A
	T _A = 85°C		± 0.50	± 0.48	-0.43	-0.41	
Pulsed Drain Current		I_{DM}	± 1.0				A
Continuous Source Current (Diode Conduction) ^a		I_S	0.25	0.23	-0.25	-0.23	
Maximum Power Dissipation ^a	T _A = 25°C	P_D	0.30	0.27	0.30	0.27	W
	T _A = 85°C		0.16	0.14	0.16	0.14	
Operating Junction and Storage Temperature Range	T _J , T _{stg}		-55 to 150				°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	t ≤ 5 sec	R _{thJA}	360	415	°C/W
	Steady State		400	460	
Maximum Junction-to-Foot (Drain)		R _{thJF}	300	350	

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

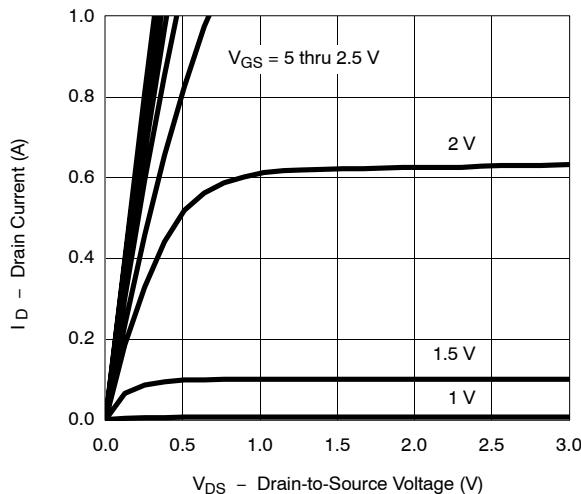
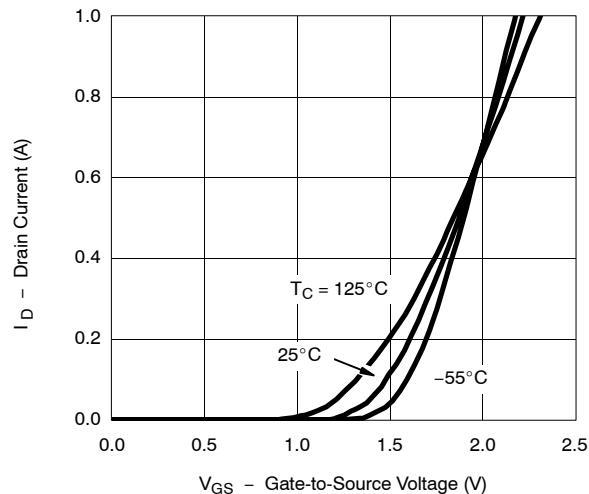
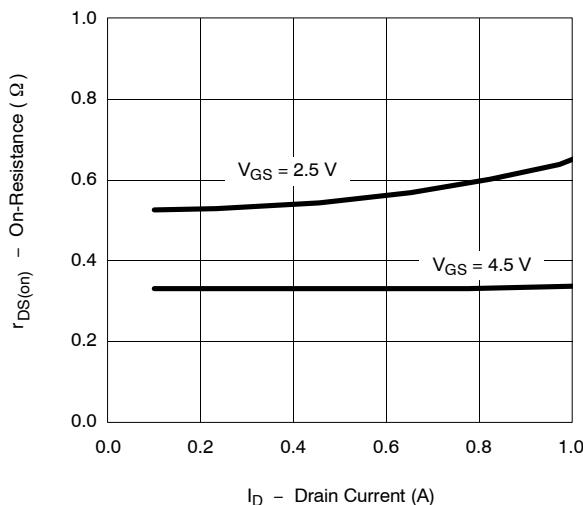
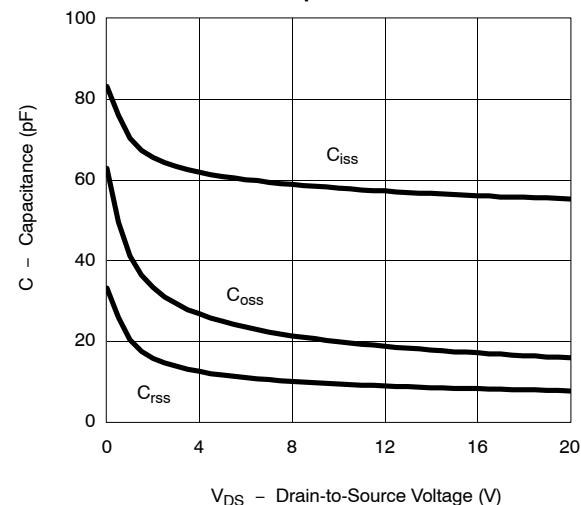
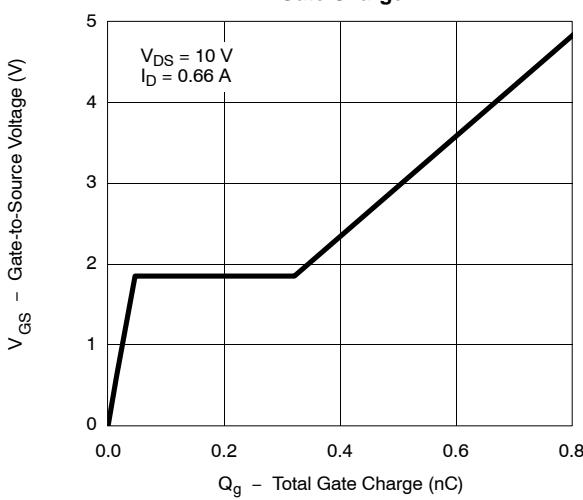
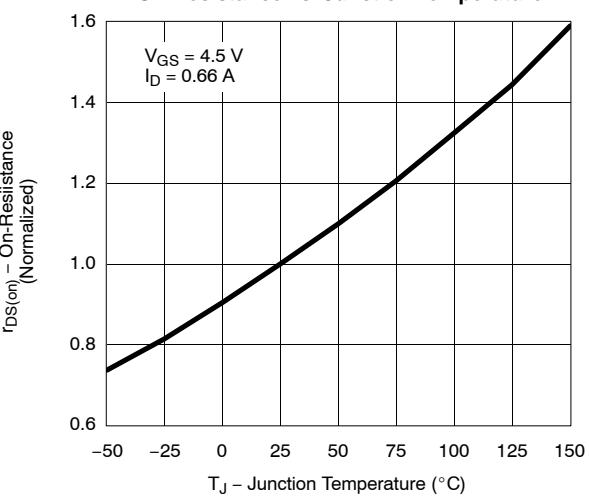
SPECIFICATIONS ($T_J = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	N-Ch	0.6		1.4
		$V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$	P-Ch	-0.45		-1.0
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$	N-Ch			± 100
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$	P-Ch			± 100
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	N-Ch		1	
		$V_{DS} = -8 \text{ V}, V_{GS} = 0 \text{ V}$	P-Ch		-1	
		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 85^\circ\text{C}$	N-Ch		5	
		$V_{DS} = -8 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 85^\circ\text{C}$	P-Ch		-5	
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} \geq 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	N-Ch	1.0		
		$V_{DS} \leq -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	P-Ch	-1.0		
Drain-Source On-State Resistance ^a	$r_{DS(\text{on})}$	$V_{GS} = 4.5 \text{ V}, I_D = 0.66 \text{ A}$	N-Ch		0.320	0.385
		$V_{GS} = -4.5 \text{ V}, I_D = -0.57 \text{ A}$	P-Ch		0.510	0.600
		$V_{GS} = 2.5 \text{ V}, I_D = 0.40 \text{ A}$	N-Ch		0.560	0.630
		$V_{GS} = -2.5 \text{ V}, I_D = -0.48 \text{ A}$	P-Ch		0.720	0.850
		$V_{GS} = -1.8 \text{ V}, I_D = -0.20 \text{ A}$	P-Ch		1.00	1.200
Forward Transconductance ^a	g_{fs}	$V_{DS} = 10 \text{ V}, I_D = 0.66 \text{ A}$	N-Ch		1.5	
		$V_{DS} = -4 \text{ V}, I_D = -0.57 \text{ A}$	P-Ch		1.2	
Diode Forward Voltage ^a	V_{SD}	$I_S = 0.23 \text{ A}, V_{GS} = 0 \text{ V}$	N-Ch		0.8	1.2
		$I_S = -0.23 \text{ A}, V_{GS} = 0 \text{ V}$	P-Ch		-0.8	-1.2
Dynamic^b						
Total Gate Charge	Q_g	N-Channel $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 0.66 \text{ A}$ P-Channel $V_{DS} = -4 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -0.57 \text{ A}$	N-Ch		0.8	1.2
Gate-Source Charge	Q_{gs}		P-Ch		1.5	2.3
Gate-Drain Charge	Q_{gd}		N-Ch		0.06	
Gate-Drain Charge	Q_{gd}		P-Ch		0.17	
Turn-On Delay Time	$t_{d(\text{on})}$	N-Channel $V_{DD} = 10 \text{ V}, R_L = 20 \Omega$ $I_D \approx 0.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 6 \Omega$ P-Channel $V_{DD} = -4 \text{ V}, R_L = 8 \Omega$ $I_D \approx -0.5 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 6 \Omega$	N-Ch		10	20
Rise Time	t_r		P-Ch		6	12
Turn-Off Delay Time	$t_{d(\text{off})}$		N-Ch		16	30
Fall Time	t_f		P-Ch		25	50
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = 0.23 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$	N-Ch		10	20
		$I_F = -0.23 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$	P-Ch		10	20

Notes

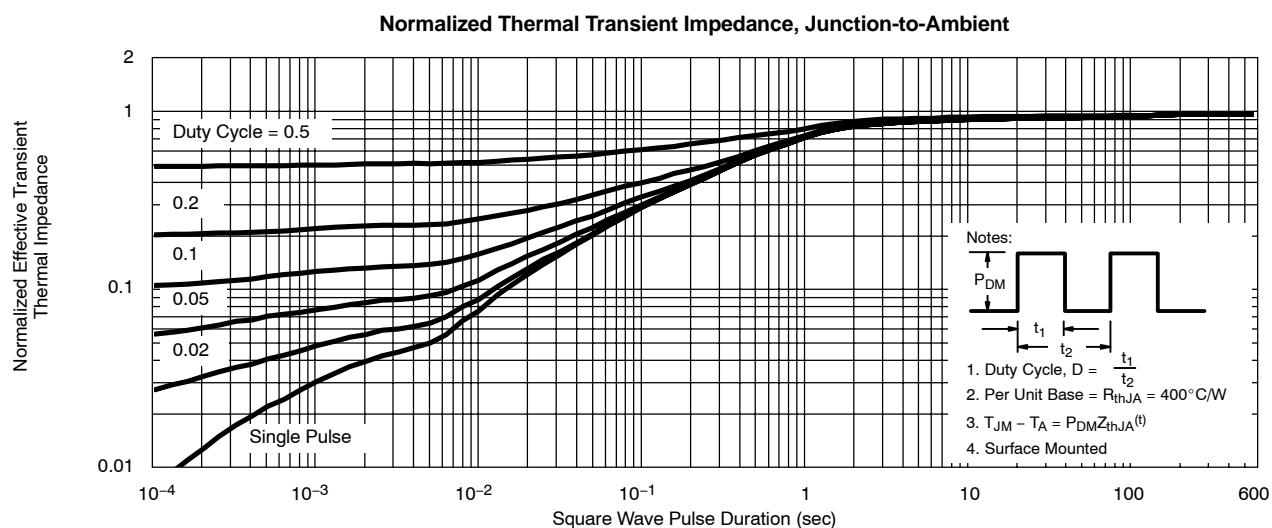
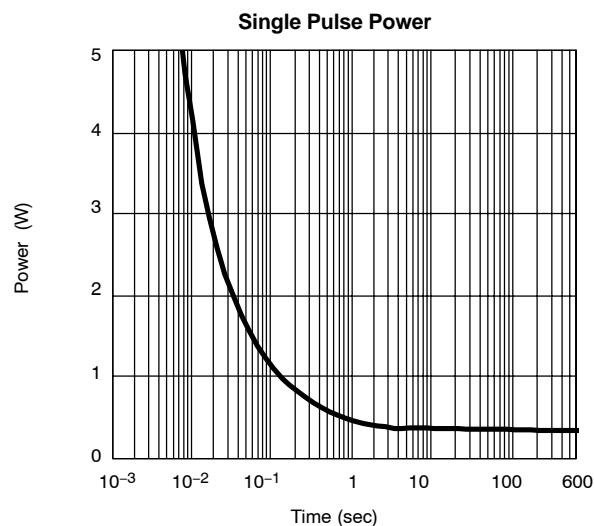
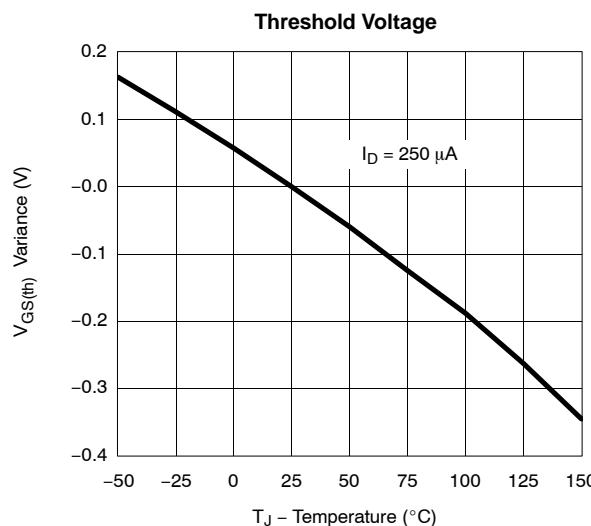
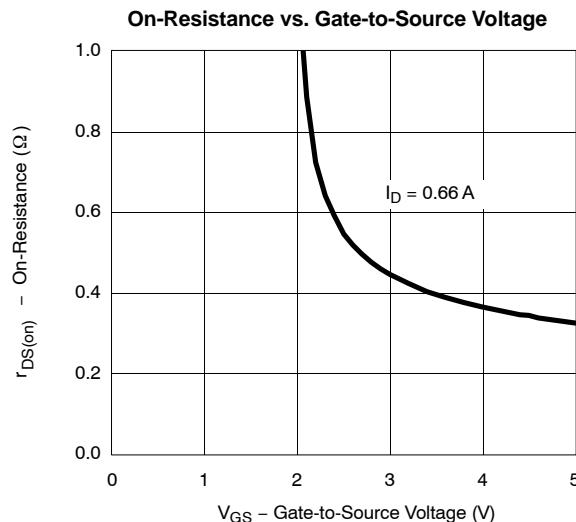
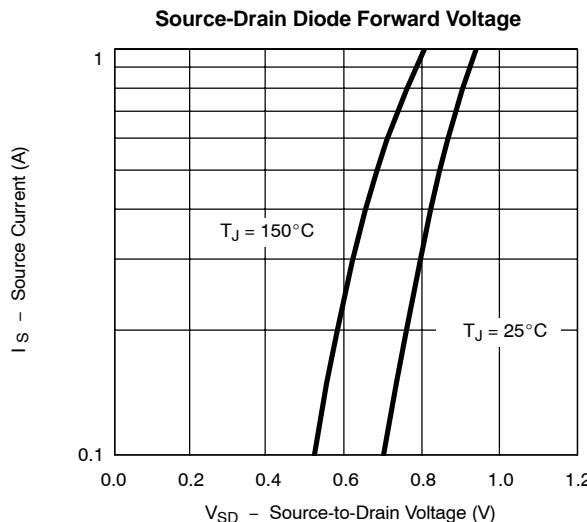
- a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)
N-CHANNEL
Output Characteristics

Transfer Characteristics

On-Resistance vs. Drain Current

Capacitance

Gate Charge

On-Resistance vs. Junction Temperature


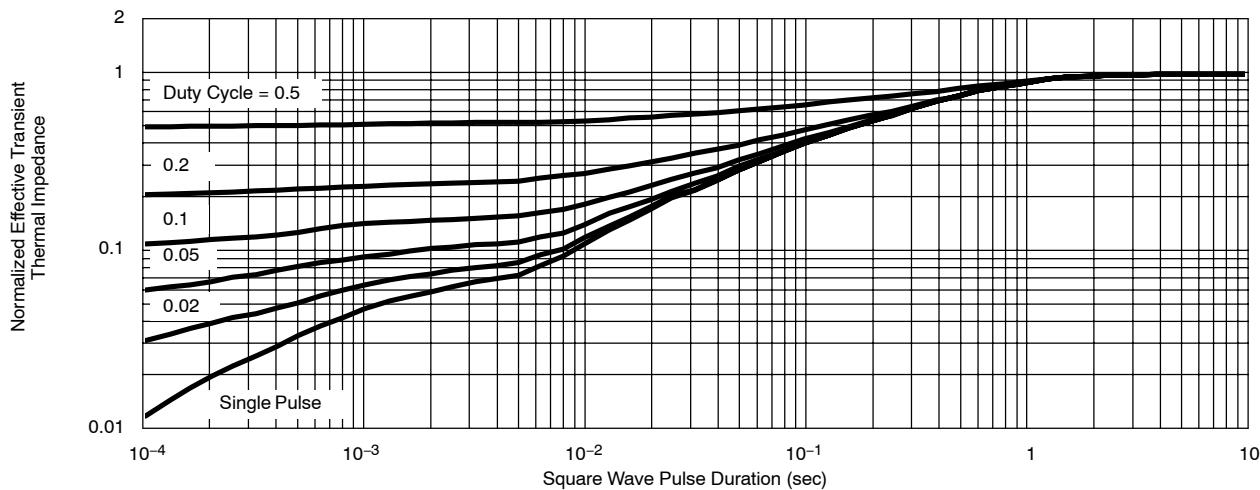
TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

N-CHANNEL

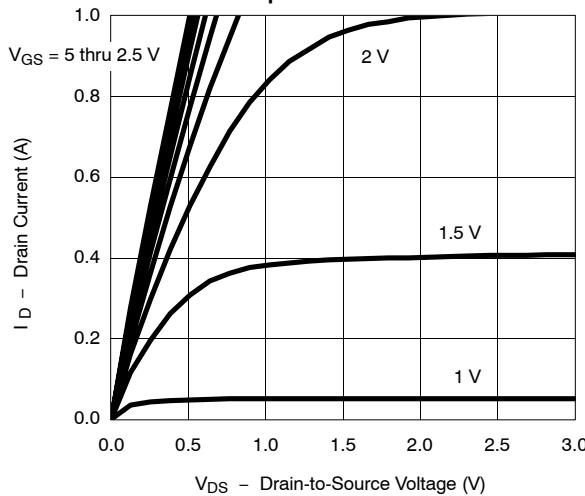


TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)
N-CHANNEL

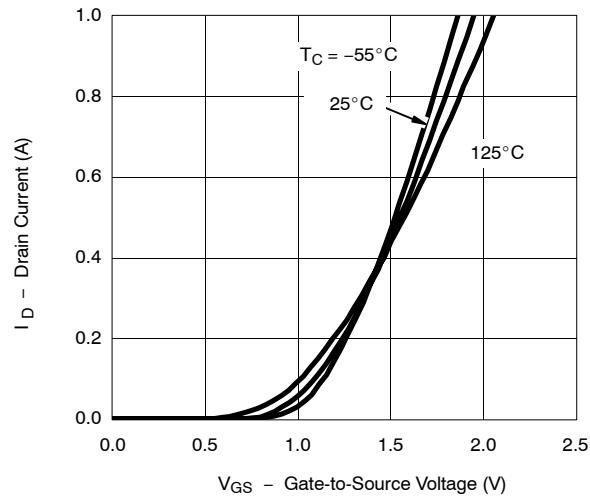
Normalized Thermal Transient Impedance, Junction-to-Foot


TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)
P-CHANNEL

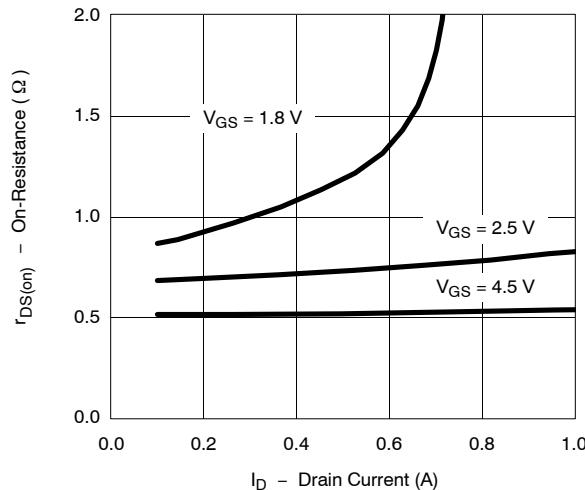
Output Characteristics



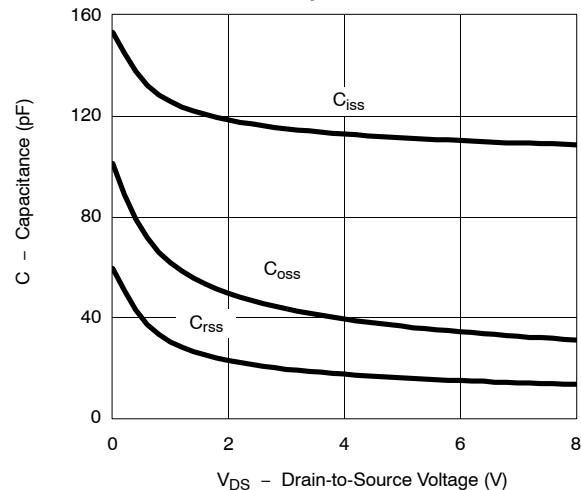
Transfer Characteristics



On-Resistance vs. Drain Current



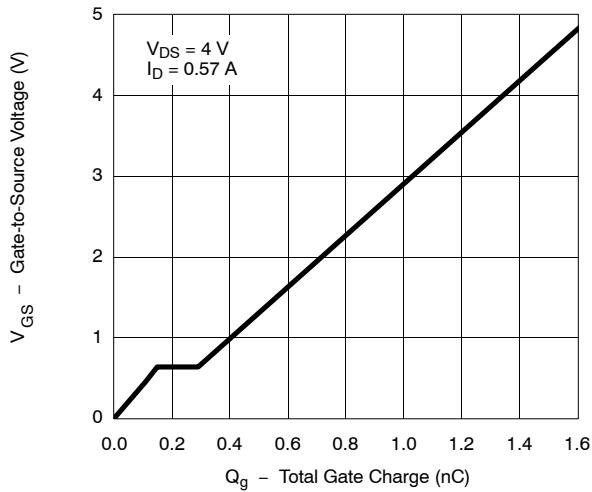
Capacitance



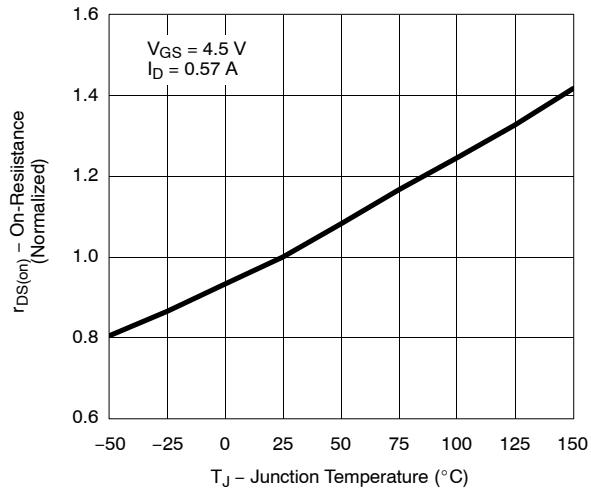
TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

P-CHANNEL

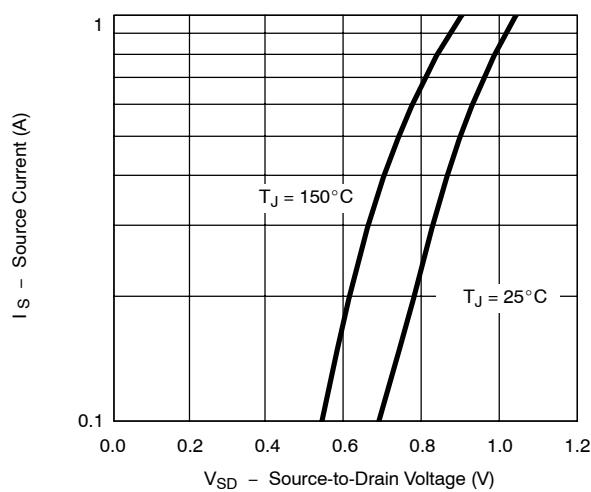
Gate Charge



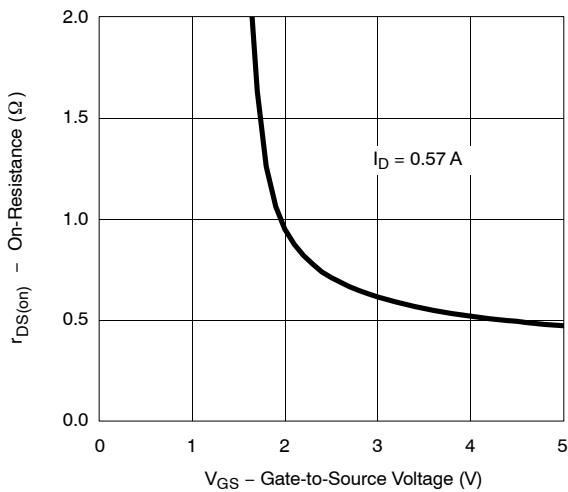
On-Resistance vs. Junction Temperature



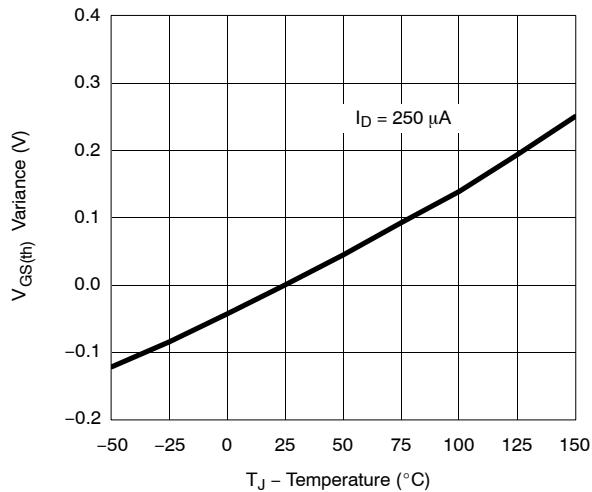
Source-Drain Diode Forward Voltage



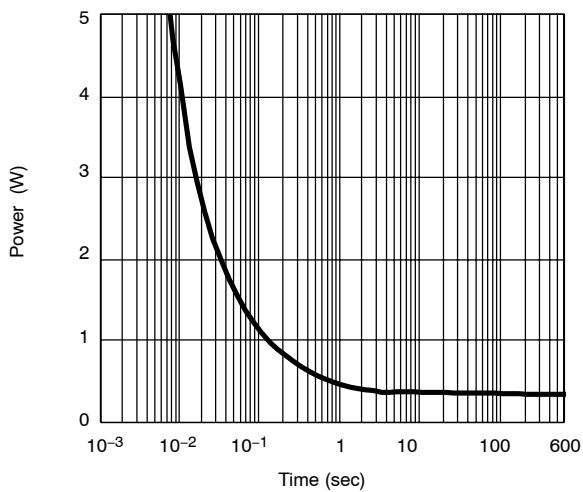
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

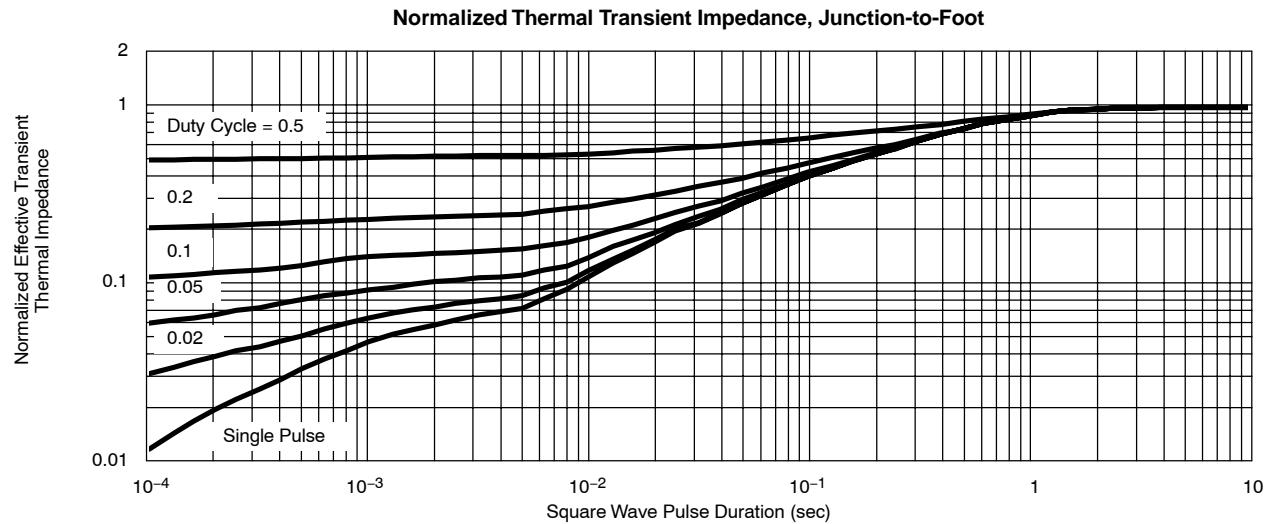
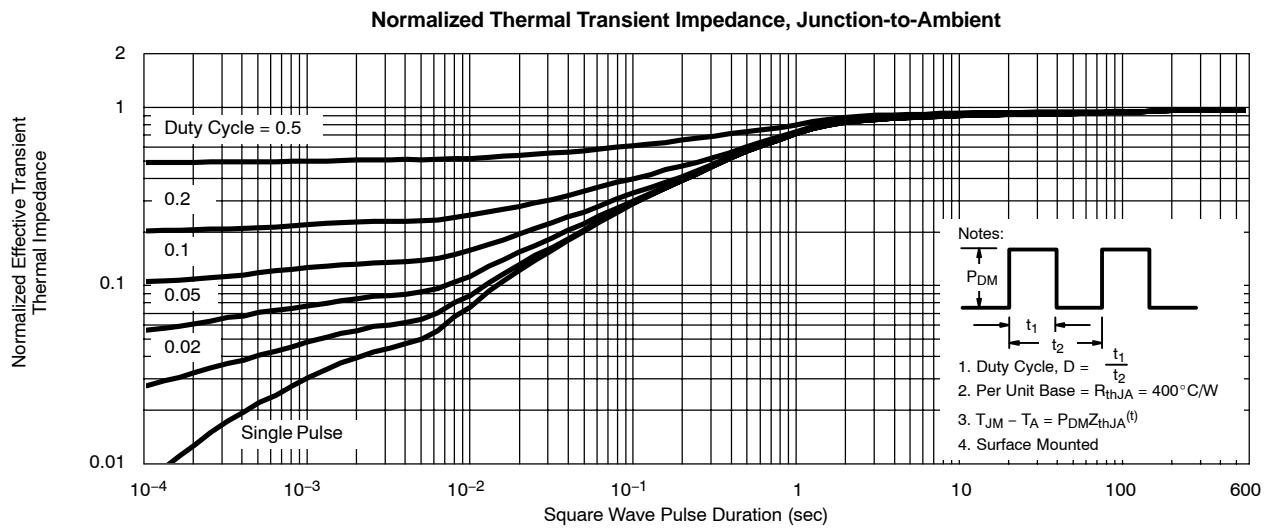


Single Pulse Power



TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

P-CHANNEL



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